

ABSTRACT

Technology Design of lead-tin alloy plating on the conductive pattern printed circuit boards in an automatic line.

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Designed workshop for production of printed circuit boards. For a good soldering the project developed technology of shiny coating with tin-lead alloy of fluoroborate electrolyte additives Limeda POS-1 and DS-10 Syntanol. Our calculation process and layout galvanic line capacity of 96,000 cards / year.

The project envisages measures for safety and automation of process parameters, proposed schemes of regeneration and utilization components of the electrolyte for electroplating with tin - lead alloy, designed the main technical and economic indicators.

Keywords: tin-lead alloy plating, current density, plating baths, a current source, print circuit board, fluoroborate electrolyte, the conductive drawing, the automatic line.

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